

FIG. 1(B)

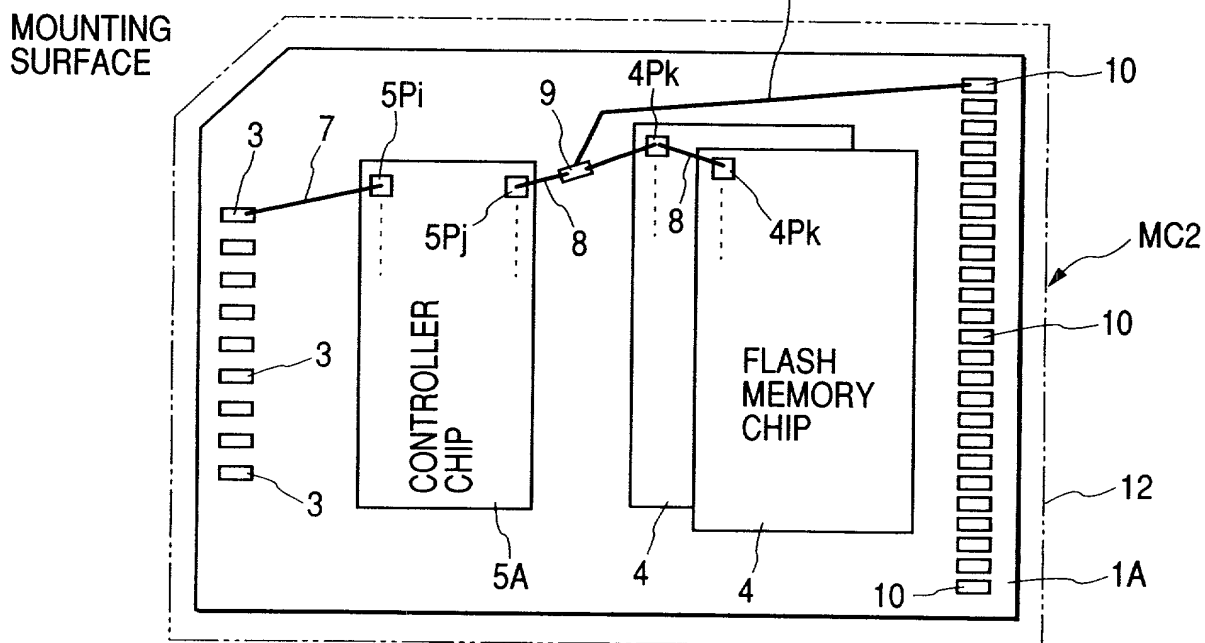


FIG. 2(B)

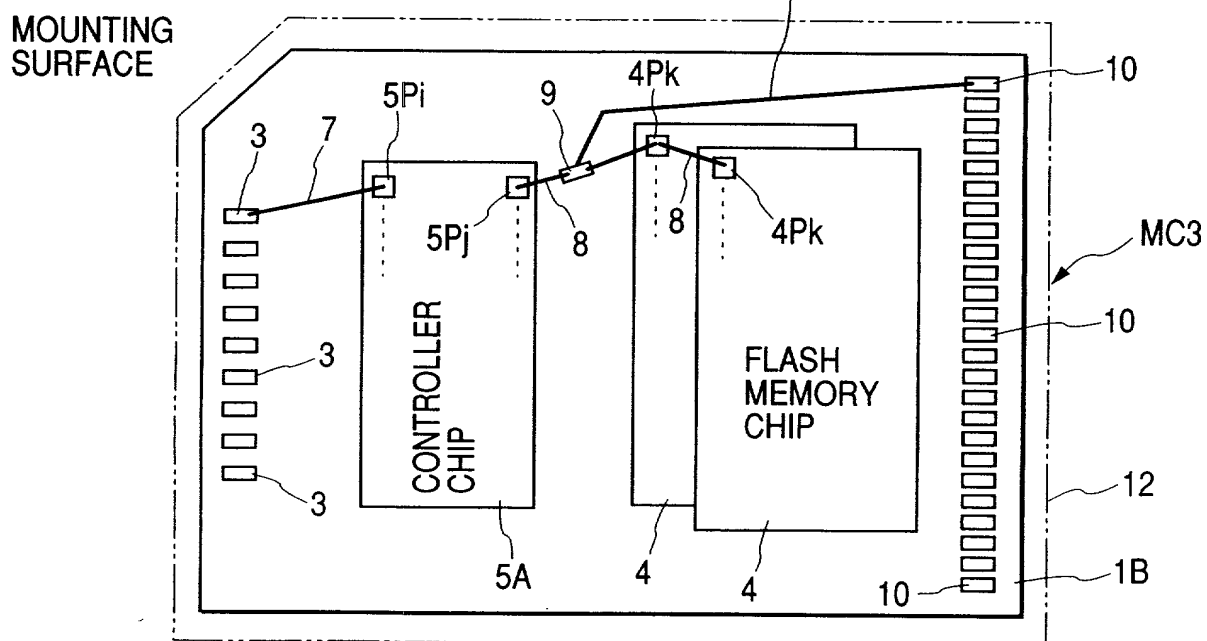


FIG. 3(A)

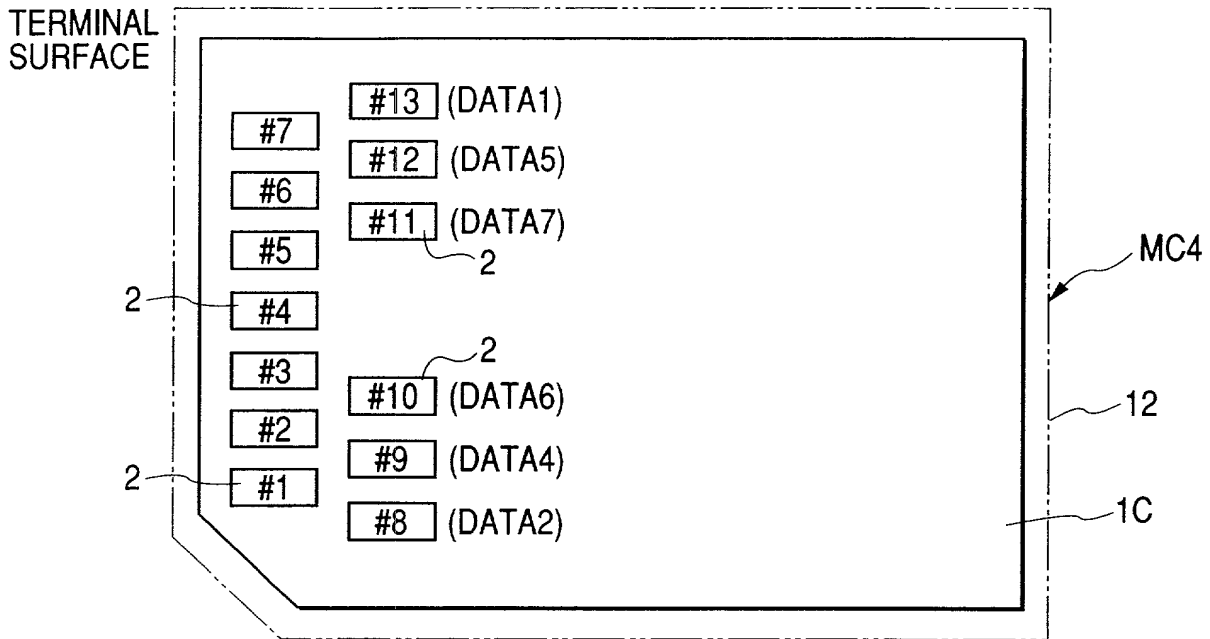


FIG. 3(B)

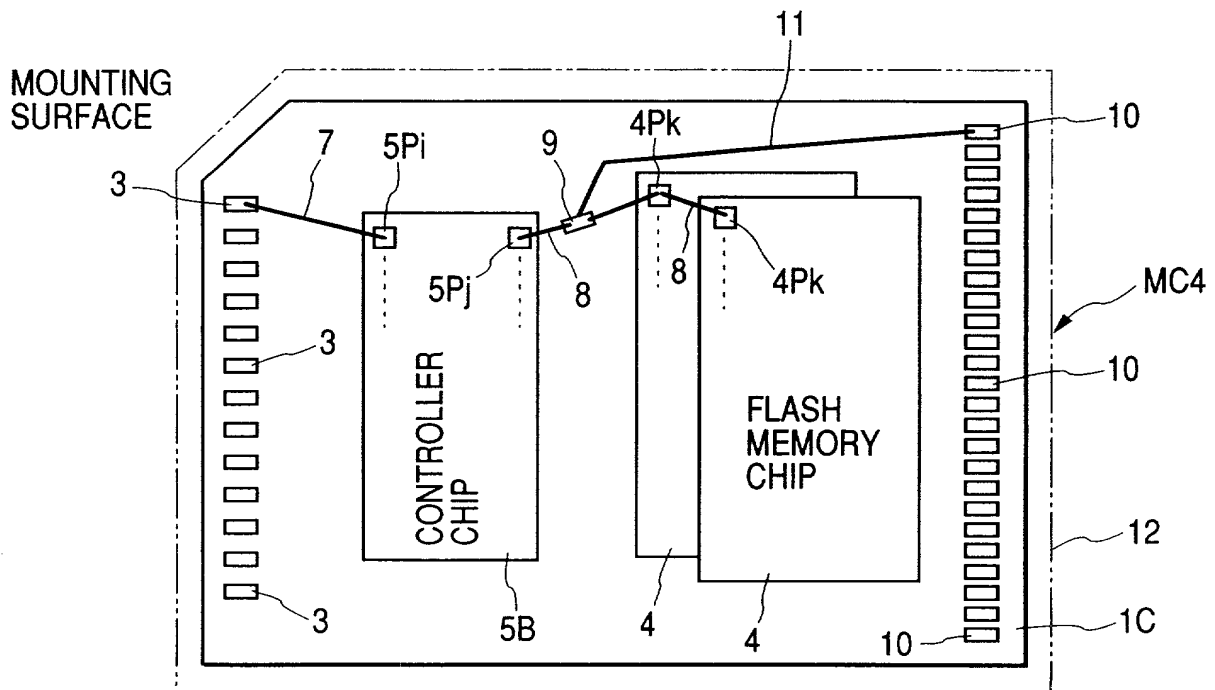


FIG. 4(A)

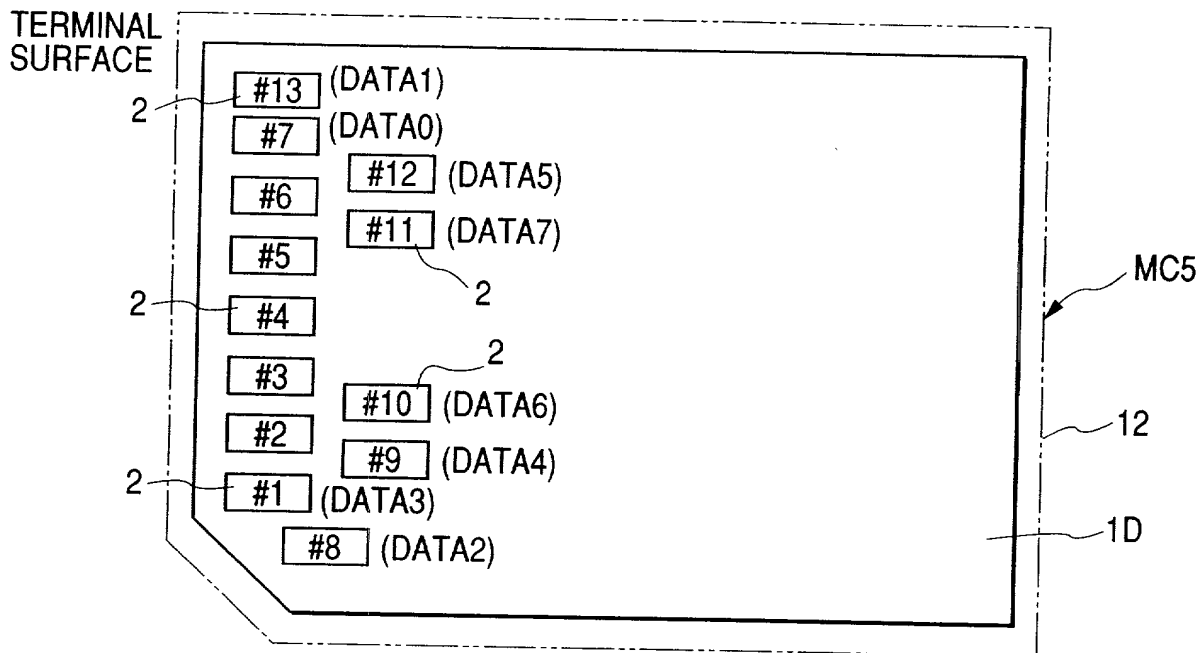


FIG. 4(B)

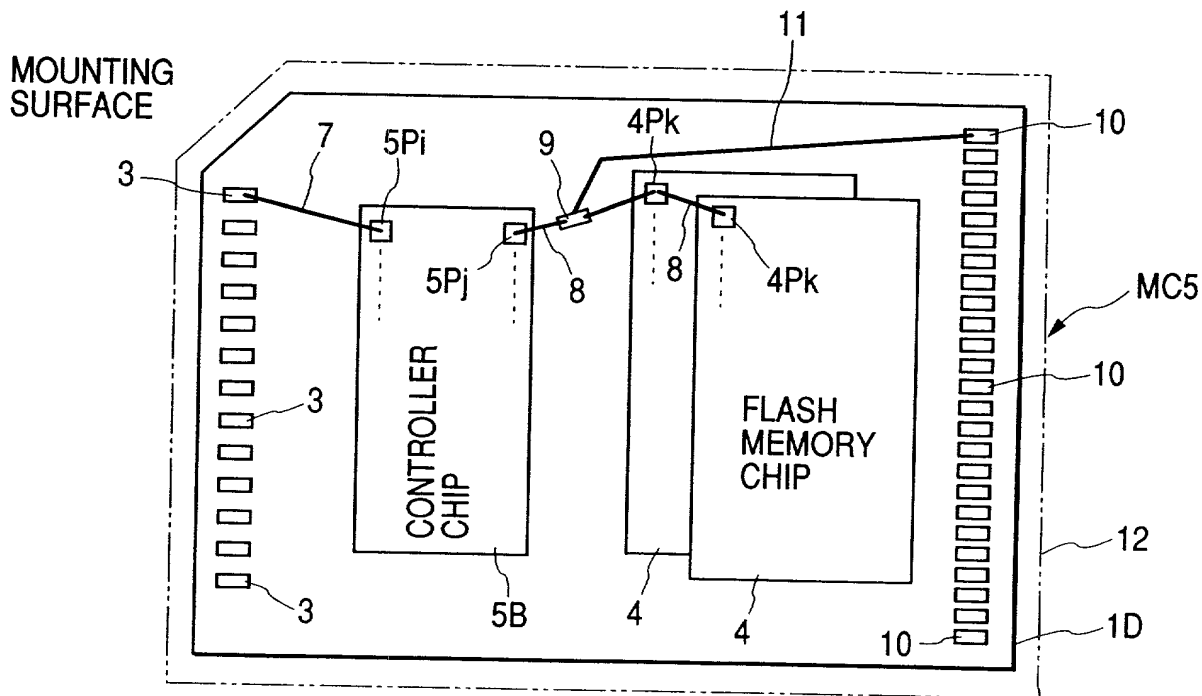


FIG. 1 is a schematic diagram of a terminal surface 1E. The terminal surface 1E is defined by a dashed line 12. A component MC6 is located on the right side of the terminal surface 1E. The terminal surface 1E is divided into a grid of 13 numbered data points, each labeled with a number and a corresponding data label in parentheses: #1 (DATA3), #2 (DATA4), #3 (DATA6), #4 (DATA2), #5 (DATA7), #6 (DATA5), #7 (DATA1), #8 (DATA2), #9 (DATA4), #10 (DATA6), #11 (DATA7), #12 (DATA5), and #13 (DATA1). The points are arranged in two columns. The left column contains points #1 through #7, and the right column contains points #8 through #13. A dimension '2' is shown between points #5 and #6, and between points #3 and #4. A label 'TERMINAL SURFACE' is located at the top left, and '(DATA0)' is located near the top left corner.

FIG. 1 is a perspective view of a semiconductor package 10. The package 10 is shown with a mounting surface 3. On the mounting surface 3, there are two chips: a controller chip 5 and a flash memory chip 4. The controller chip 5 is labeled "CONTROLLER CHIP" and has pins 5Pi and 5Pj. The flash memory chip 4 is labeled "FLASH MEMORY CHIP" and has pins 4Pk. The package 10 is also labeled MC6. The mounting surface 3 is shown with pins 3. The package 10 is shown with a top surface 11 and a bottom surface 12. The package 10 is shown with a side surface 1E. The package 10 is shown with a front surface 10. The package 10 is shown with a back surface 10. The package 10 is shown with a left surface 10 and a right surface 10.

FIG. 6(B)

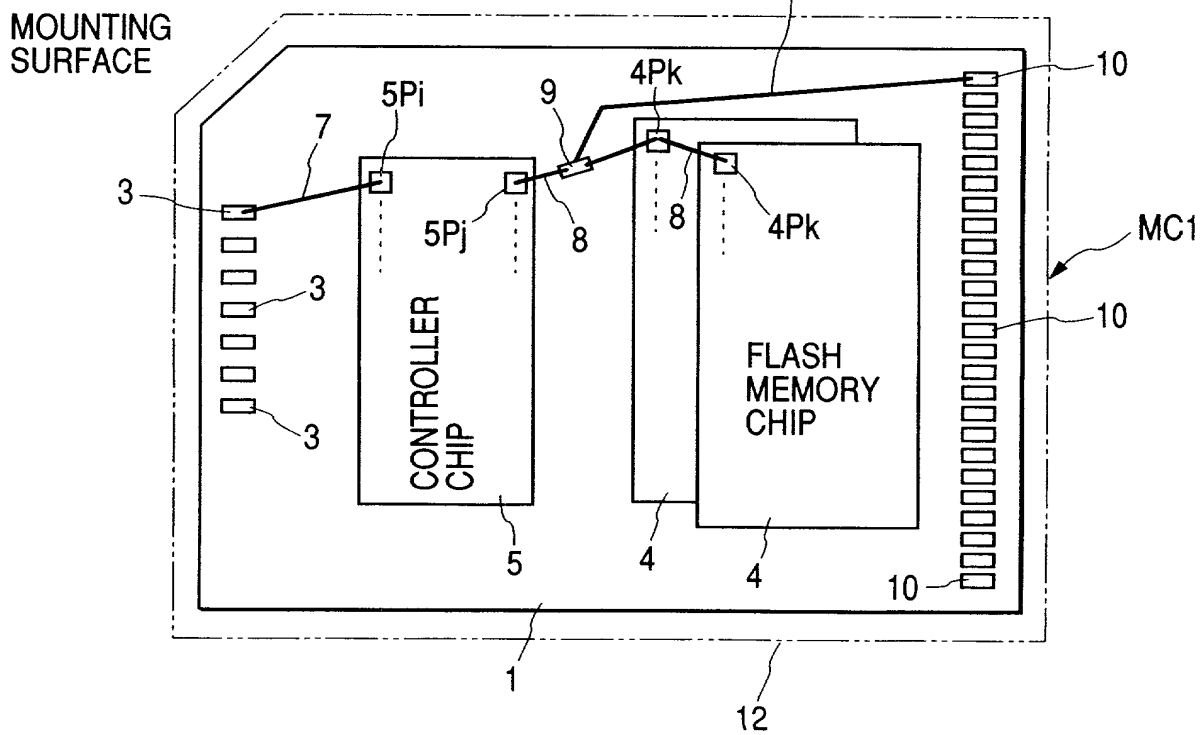


FIG. 8

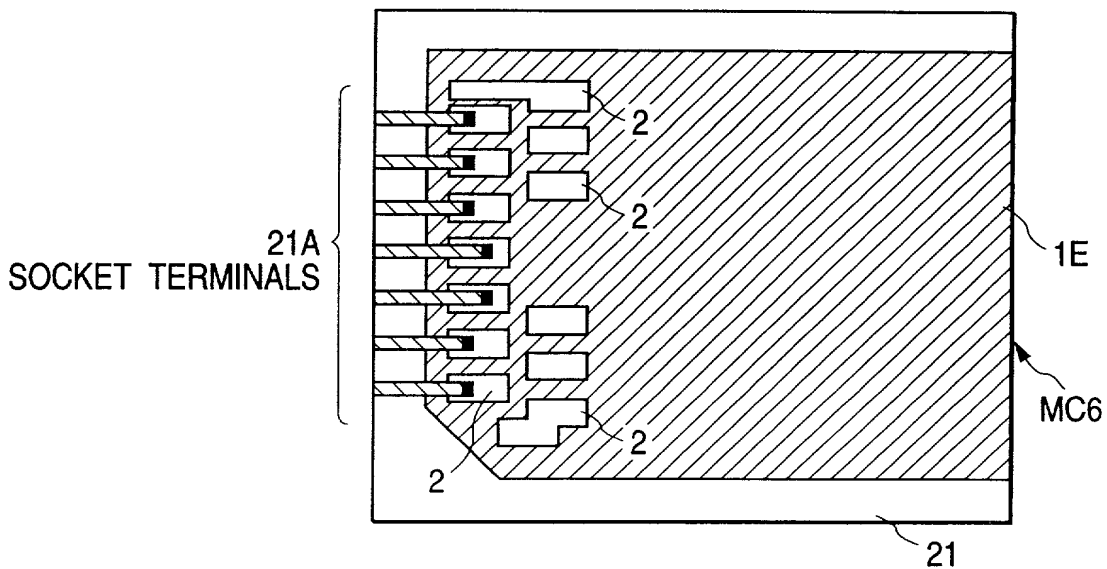


FIG. 9

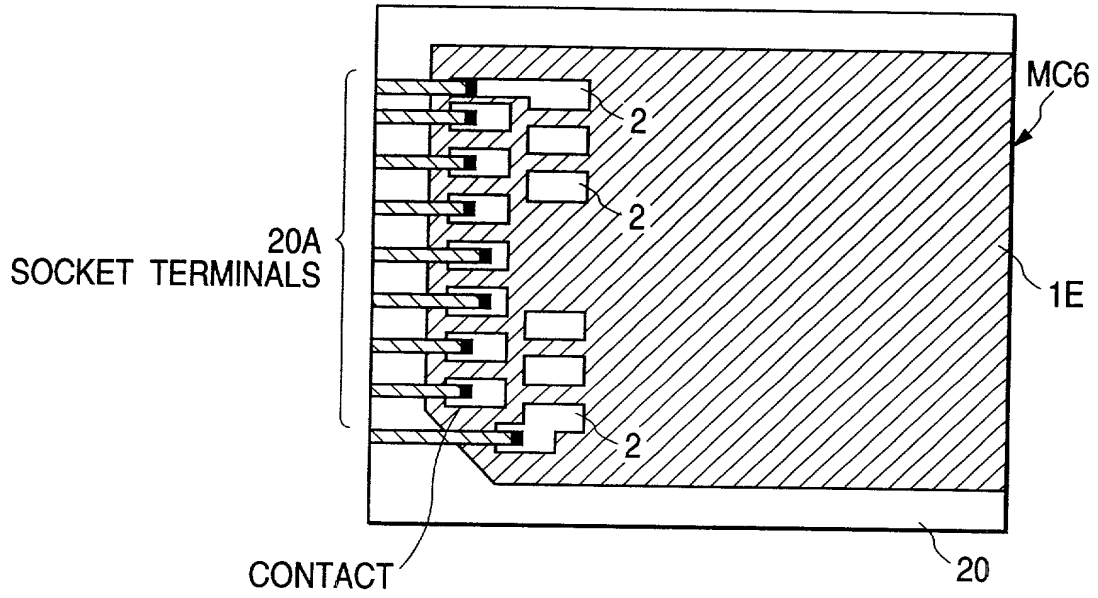


FIG. 10

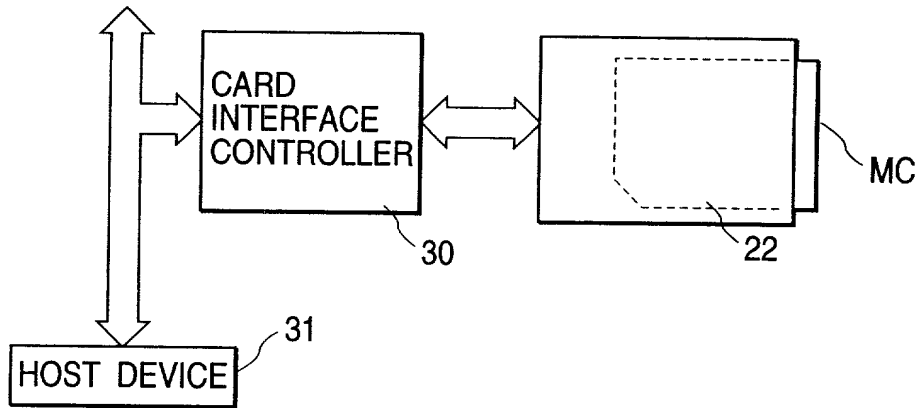


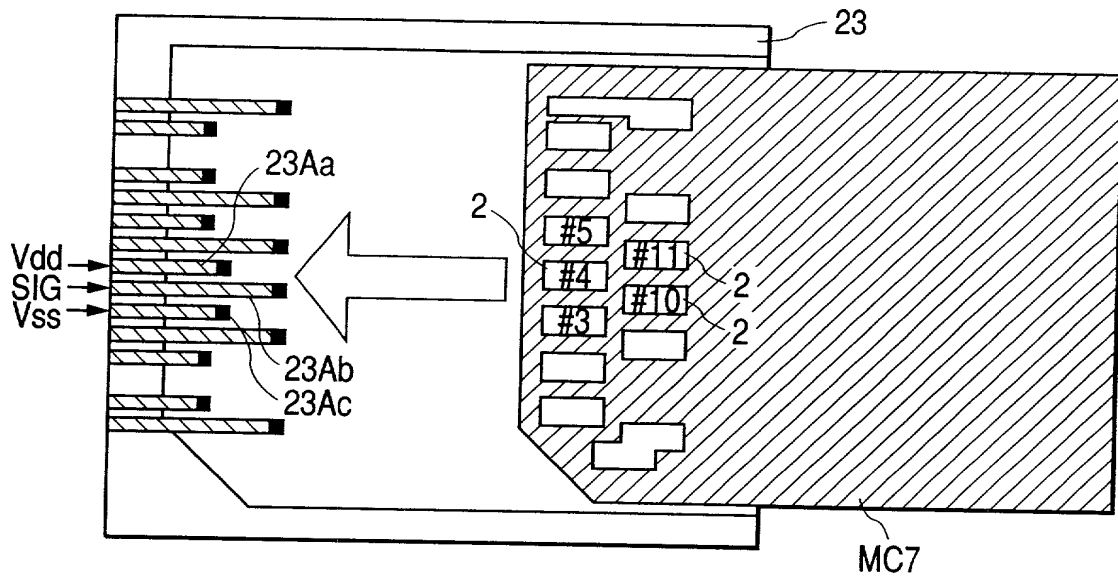
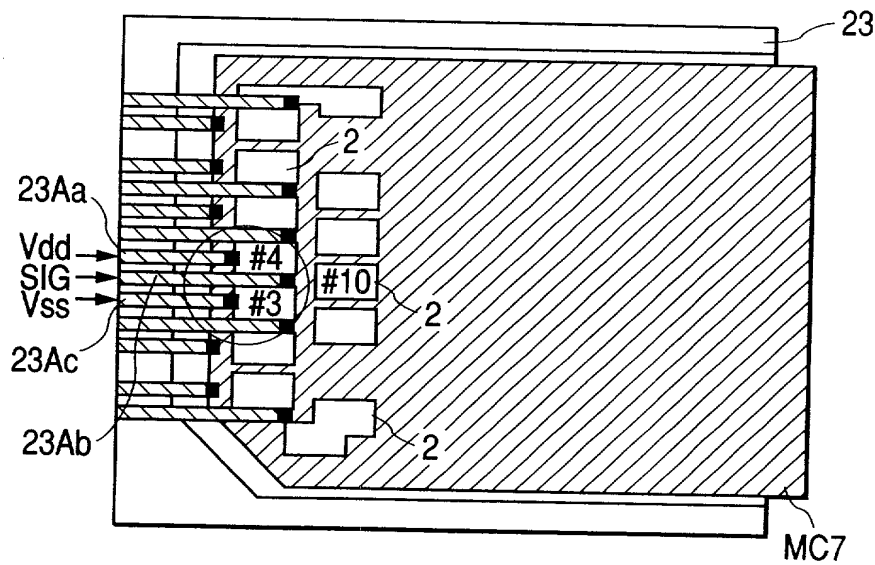
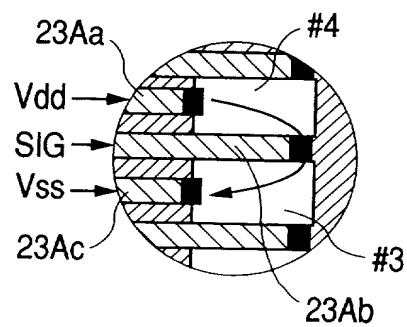
FIG. 11(A)**FIG. 11(B)****FIG. 11(C)**

FIG. 12

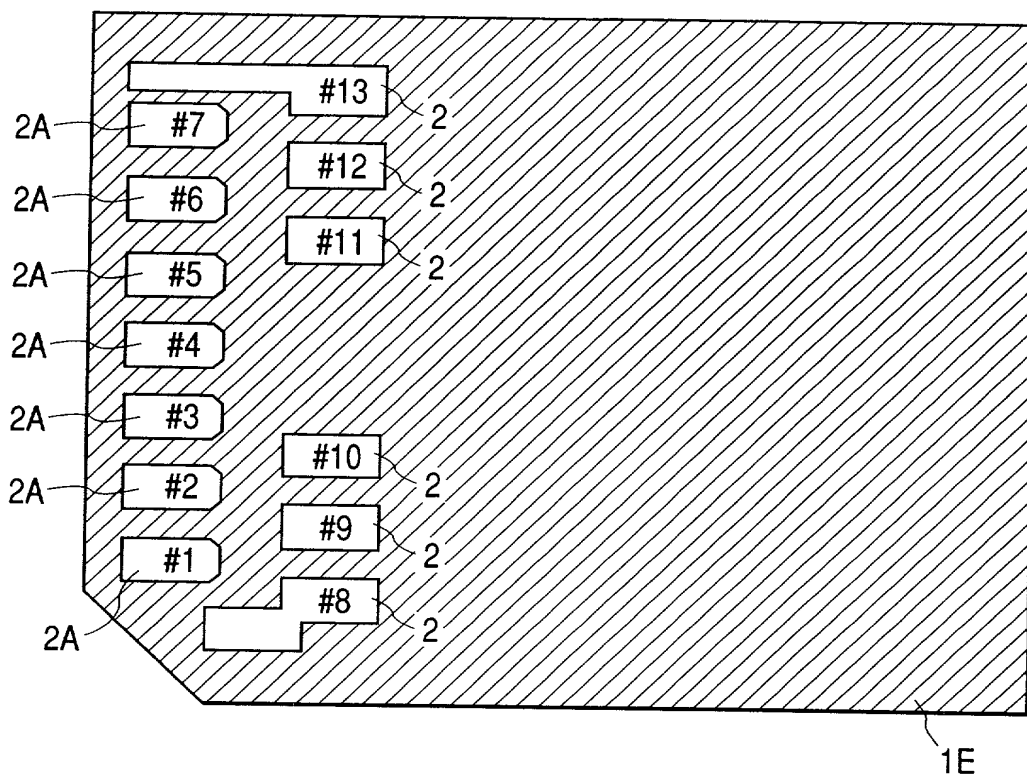


FIG. 13

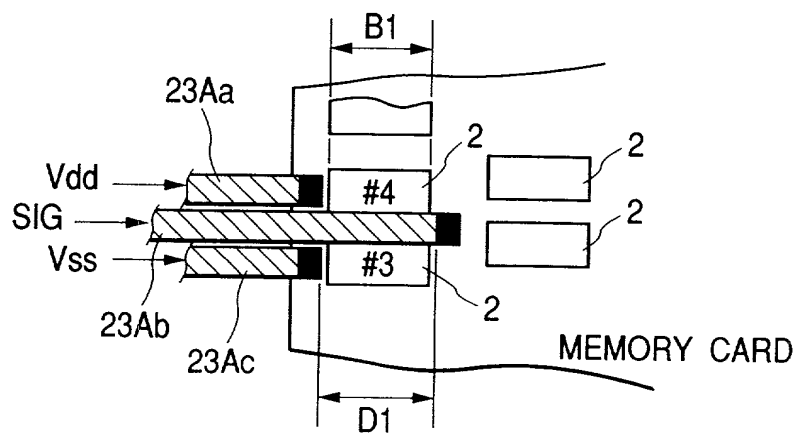


FIG. 14

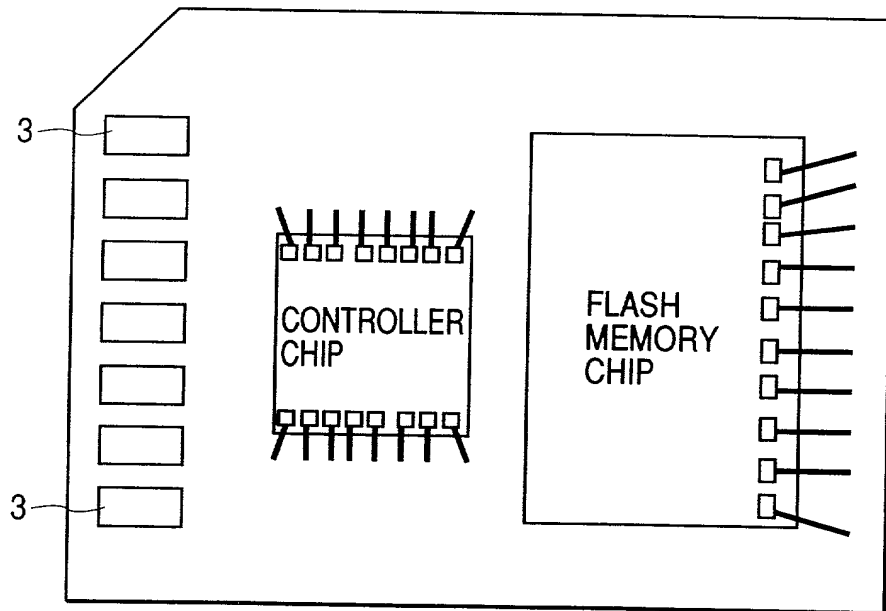


FIG. 16

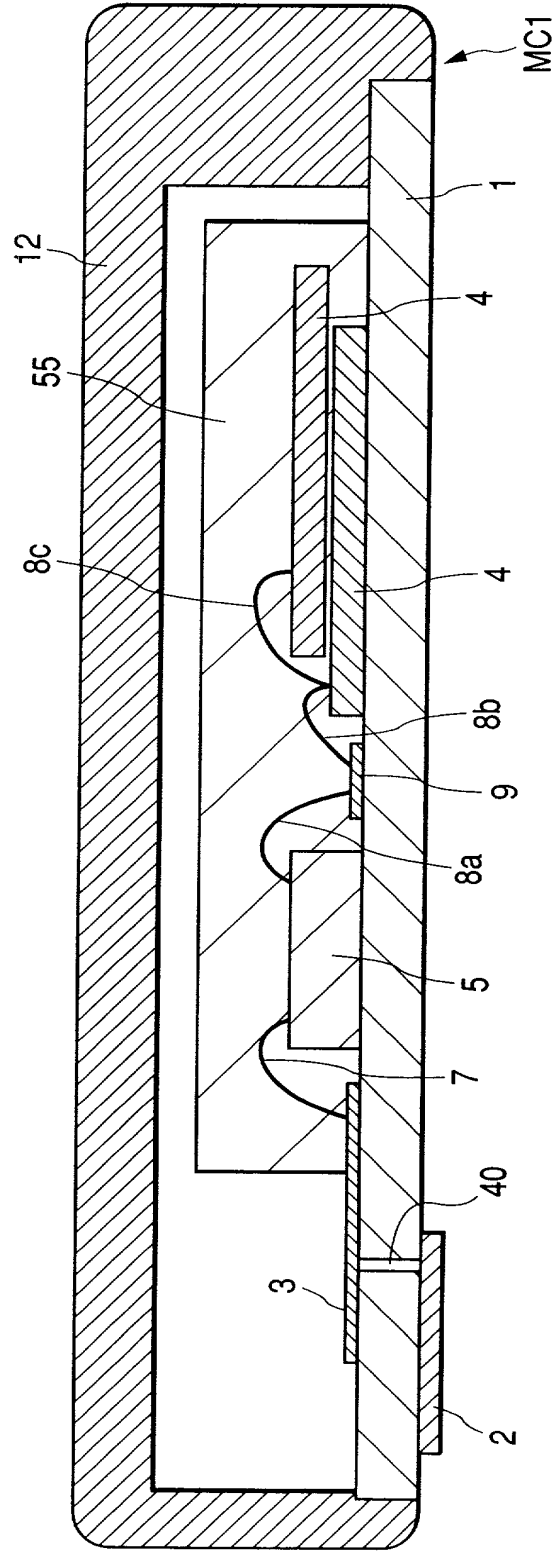


FIG. 17

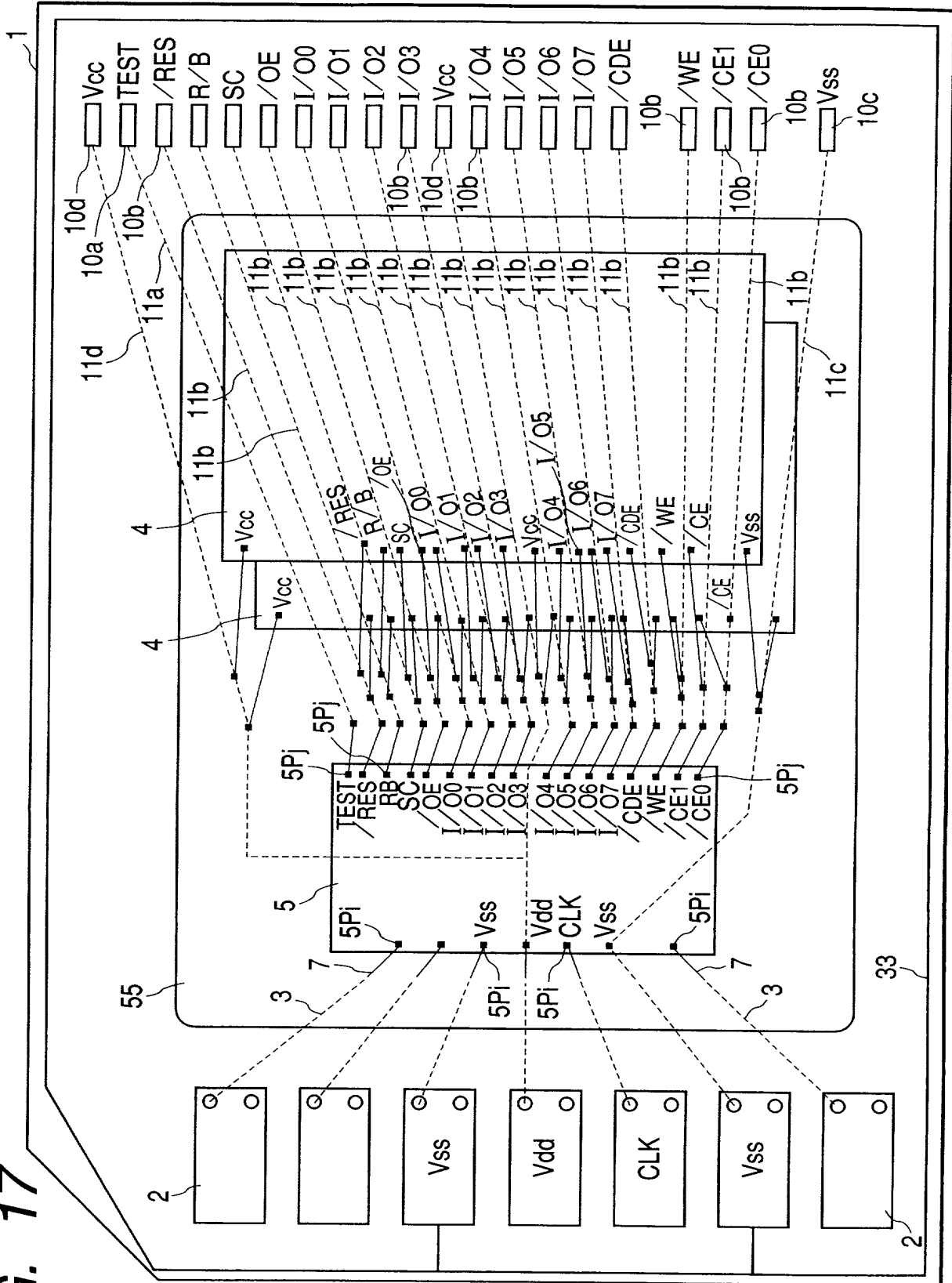


FIG. 18

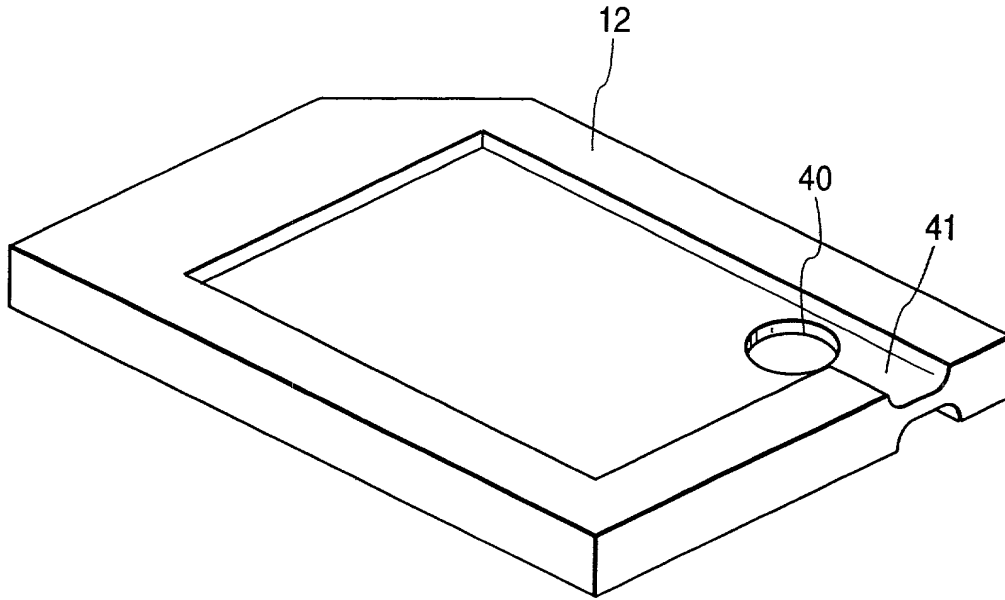


FIG. 19

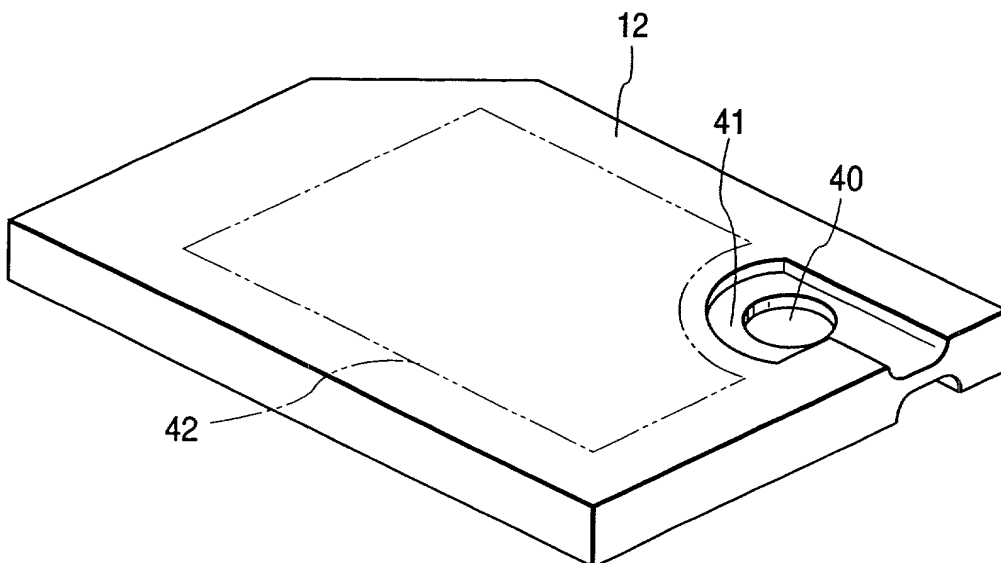


FIG. 20

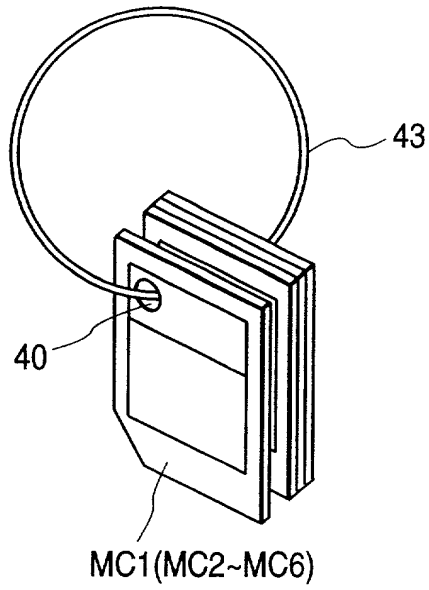
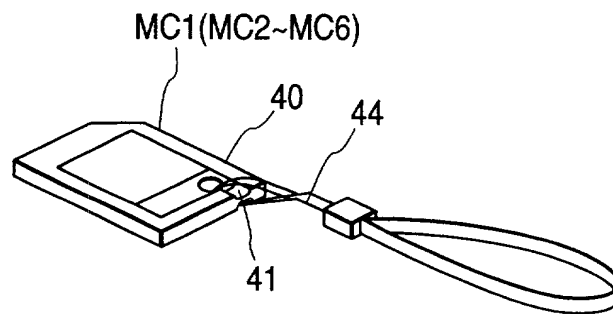


FIG. 21



Declaration and Power of Attorney For Patent Application

特許出願宣言書及び委任状

Japanese Language Declaration

日本語宣言書

下記の氏名の発明者として、私は以下の通り宣言します。

As a below named inventor, I hereby declare that.

私の住所、私書箱、国籍は下記の私の氏名の後に記載された通りです。

My residence, post office address and citizenship are as stated next to my name.

下記の名称の発明に関して請求範囲に記載され、特許出願している発明内容について、私が最初かつ唯一の発明者（下記の氏名が一つの場合）もしくは最初かつ共同発明者であると（下記の名称が複数の場合）信じています。

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

IC CARD

上記発明の明細書（下記の欄で×印がついていない場合は、本書に添付）は、

The specification of which is attached hereto unless the following box is checked:

☐ __月__日に提出され、米国出願番号または特許協定条約国際出願番号を____とし、
(該当する場合) _____に訂正されました。

☐ was filed on
as United States Application Number or
PCT International Application Number
_____ and was amended on
_____ (if applicable).

私は、特許請求範囲を含む上記訂正後の明細書を検討し、内容を理解していることをここに表明します。

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above

私は、連邦規則法典第37編第1条56項に定義されるとおり、特許資格の有無について重要な情報を開示する義務があることを認めます。

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56.

Japanese Language Declaration

(日本語宣言書)

私は、米国法典第35編119条(a)-(d)項又は365条(b)項に基き下記の、米国以外の国の少なくとも一カ国を指定している特許協力条約365(a)項に基き国際出願、又は外国での特許出願もしくは発明者証の出願についての外国優先権をここに主張するとともに、優先権を主張している、本出願の前に出願された特許または発明者証の外国出願を以下に、枠内をマークすることで、示している。

Prior Foreign Application(s)

外国での先行出願

<u>2000-018030</u>	<u>Japan</u>
(Number)	(Country)
(番号)	(国名)
<u> </u>	<u> </u>
(Number)	(Country)
(番号)	(国名)

私は、第35編米国法典119条(e)項に基いて下記の米国特許出願規定に記載された権利をここに主張いたします。

<u> </u>	<u> </u>
(Application No.)	(Filing Date)
(出願番号)	(出願日)

私は、下記の米国法典第35編120条に基いて下記の米国特許出願に記載された権利、又は米国を指定している特許協力条約365条(c)に基き権利をここに主張します。また、本出願の各請求範囲の内容が米国法典第35編112条第1項又は特許協力条約で規定された方法で先行する米国特許出願に開示されていない限り、その先行米国出願書提出日以降で本出願書の日本国内または特許協力条約国際提出日までの期間中に入手された、連邦規則法典第37編1条56項で定義された特許資格の有無に関する重要な情報について開示義務があることを認識しています。

<u> </u>	<u> </u>
(Application No.)	(Filing Date)
(出願番号)	(出願日)
<u> </u>	<u> </u>
(Application No.)	(Filing Date)
(出願番号)	(出願日)

私は、私自身の知識に基づいて本宣言書中で私が行なう表明が真実であり、かつ私の入手した情報と私の信じることに基き、かつ表明が全て真実であると信じていること、さらに故意になされた虚偽の表明及びそれと同等の行為は米国法典第18編第1001条に基き、罰金または拘禁、もしくはその両方により処罰されること、そしてそのような故意による虚偽の表明を行えば、出願した、又は既に許可された特許の有効性が失われることを認識し、よってここに上記のごとく宣誓を致します。

I hereby claim foreign priority under Title 35, United States Code, Section 119 (a)-(d) or 365(b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT international application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed.

Priority Not Claimed

優先権主張なし

<u>25/January/2000</u>
(Day/Month/Year Filed)
(出願年月日)
<u> </u>
(Day/Month/Year Filed)
(出願年月日)

I hereby claim the benefit under Title 35, United States Code, Section 119(e) of any United States provisional application(s) listed below.

<u> </u>	<u> </u>
(Application No.)	(Filing Date)
(出願番号)	(出願日)

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s), or 365(c) of any PCT international application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code Section 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of application.

<u> </u>
(Status: Patented, Pending, Abandoned)
(現況: 特許許可済、係属中、放棄済)
<u> </u>
(Status: Patented, Pending, Abandoned)
(現況: 特許許可済、係属中、放棄済)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number

Japanese Language Declaration (日本語宣言書)

委任状： 私は下記の発明者として、本出願に関する一切の手続きを米特許商標局に対して遂行する弁理士または代理人として、下記の者を指名いたします。（弁理士、または代理人の氏名及び登録番号を明記のこと）

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith (list name and registration number)

Nelson H. Shapiro, Reg. No. 17,095, Mitchell W. Shapiro, Reg. No. 31,568, and the other practitioners associated with the Customer Number 20,230

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Send Correspondence to:

Customer No. 20,230

直接電話連絡先：（氏名及び電話番号）

Direct Telephone Calls to: (name and telephone number)

Telephone: (202) 467-8800

Fax: (202) 467-8900

唯一または第一発明者

Full name of sole or first inventor

Hiroataka NISHIZAWA

発明者の署名

日付

Inventor's signature

Date

Hiroataka Nishizawa 9/November/2000

住所

Residence

Fuchu, Japan

国籍

Citizenship

Japan

私書箱

Post Office Address

c/o Hitachi, Ltd., Intellectual Property Group
New Marunouchi Bldg. 5-1, Marunouchi 1-chome,
Chiyoda-ku, Tokyo 100-8220, Japan

(第二以降の共同発明者についても同様に記載し、署名をすること)

(Supply similar information and signature for second and subsequent joint inventors.)

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

第二共同発明者	Full name of second joint inventor, if any Haruji ISHIHARA	
第二共同発明者の署名	日付	Second inventor's signature Date 20/november/2000 Haruji Ishihara
住所	Residence Kawaguchi, Japan	
国籍	Citizenship Japan	
私書箱	Post Office Address c/o Hitachi, Ltd., Intellectual Property Group New Marunouchi Bldg. 5-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8220, Japan	
第三共同発明者	Full name of third joint inventor, if any Atsushi SHIRAISHI	
第三共同発明者の署名	日付	Third inventor's signature Date 17/november/2000 Atsushi Shiraishi
住所	Residence Kodaira, Japan	
国籍	Citizenship Japan	
私書箱	Post Office Address c/o Hitachi ULSI Systems Co., Ltd 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo 187-8522, Japan	
第四共同発明者	Full name of fourth joint inventor, if any Kouichi KANEMOTO	
第四共同発明者の署名	日付	Fourth inventor's signature Date 17/november/2000 Kouichi Kanemoto
住所	Residence Koganei, Japan	
国籍	Citizenship Japan	
私書箱	Post Office Address c/o Hitachi, Ltd., Intellectual Property Group New Marunouchi Bldg. 5-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8220, Japan	
第五共同発明者	Full name of fifth joint inventor, if any Yousuke YUKAWA	
第五共同発明者の署名	日付	Fifth inventor's signature Date 17/november/2000 Yousuke Yukawa
住所	Residence Kokubunji, Japan	
国籍	Citizenship Japan	
私書箱	Post Office Address c/o Hitachi, Ltd, Intellectual Property Group New Marunouchi Bldg. 5-1, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8220, Japan	

(第六以降の共同発明者についても同様に記載し、署名をすること)

(Supply similar information and signature for sixth and subsequent joint inventors.)

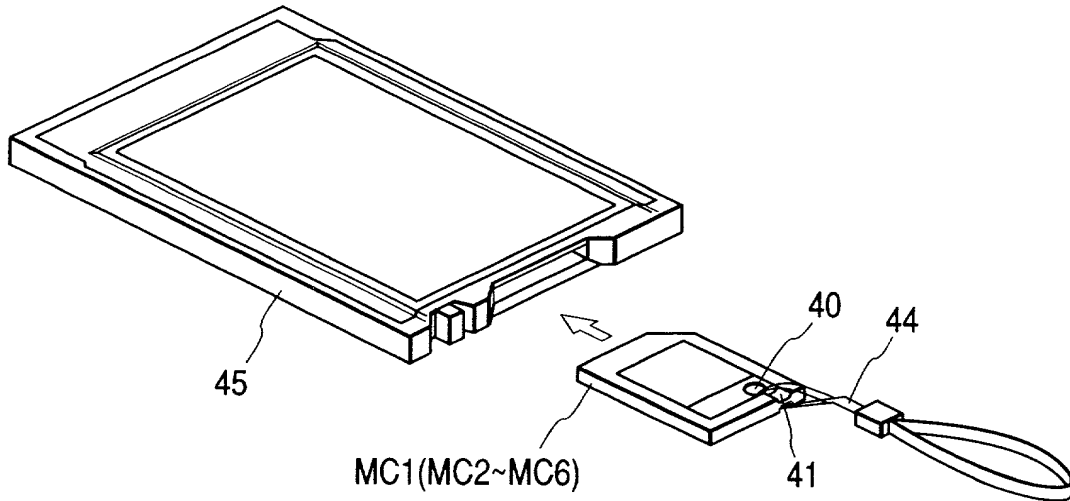
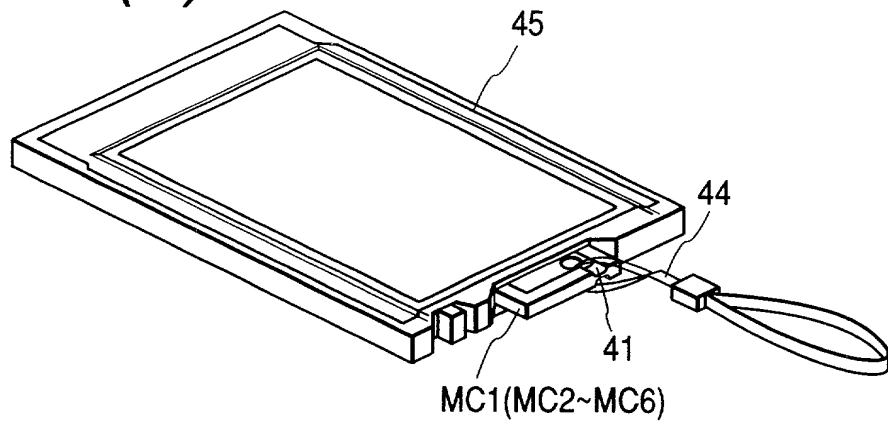
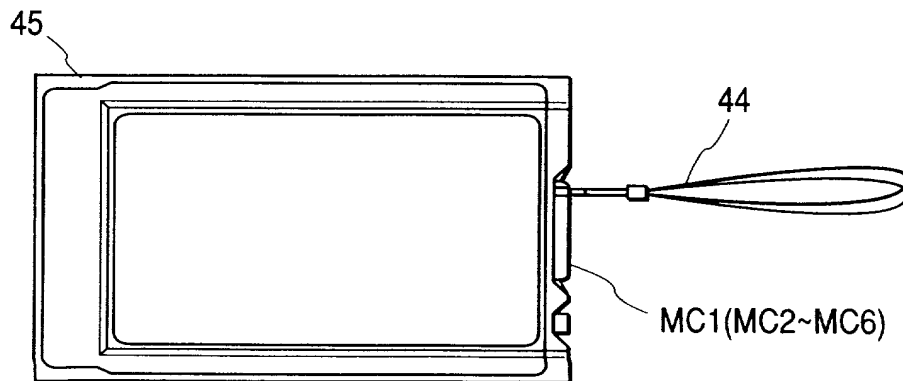
FIG. 22(A)*FIG. 22(B)**FIG. 22(C)*

FIG. 23

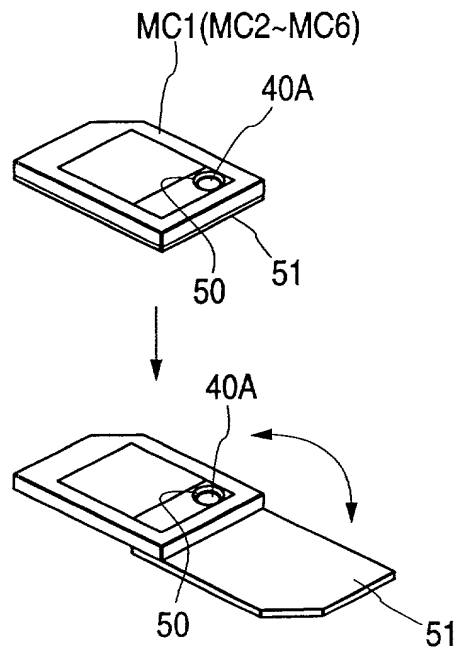


FIG. 24

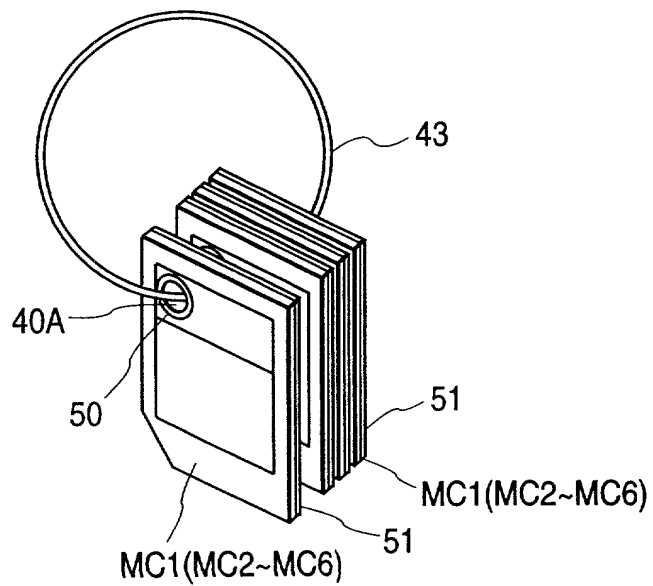


FIG. 25(A)

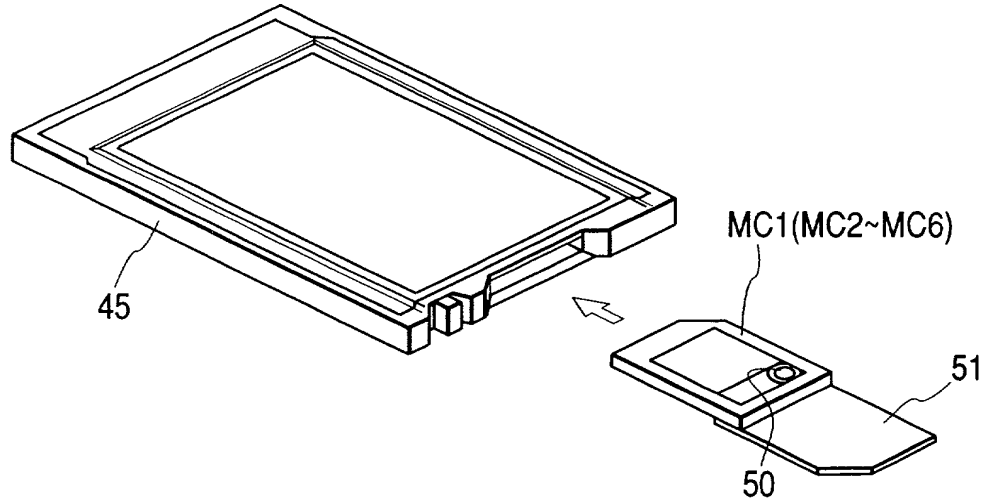


FIG. 25(B)

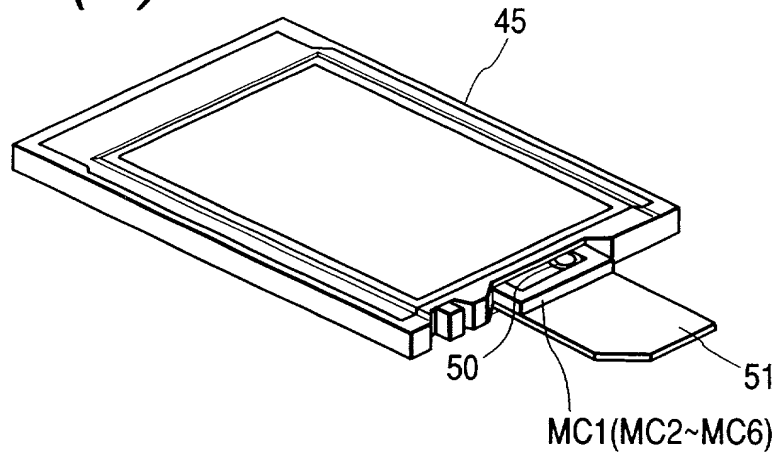


FIG. 25(C)

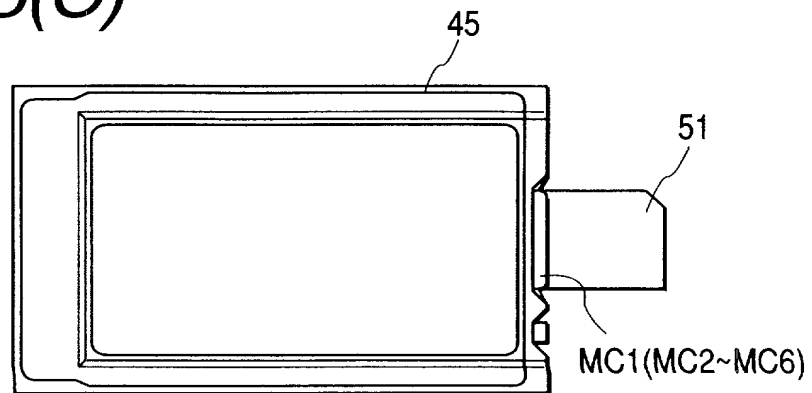


FIG. 26(B)

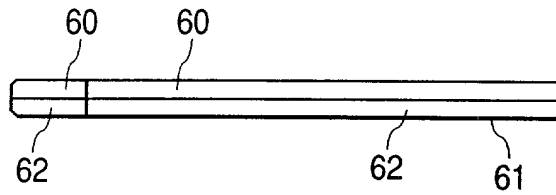


FIG. 26(C)

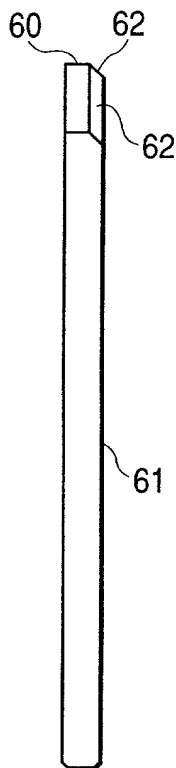


FIG. 26(A)

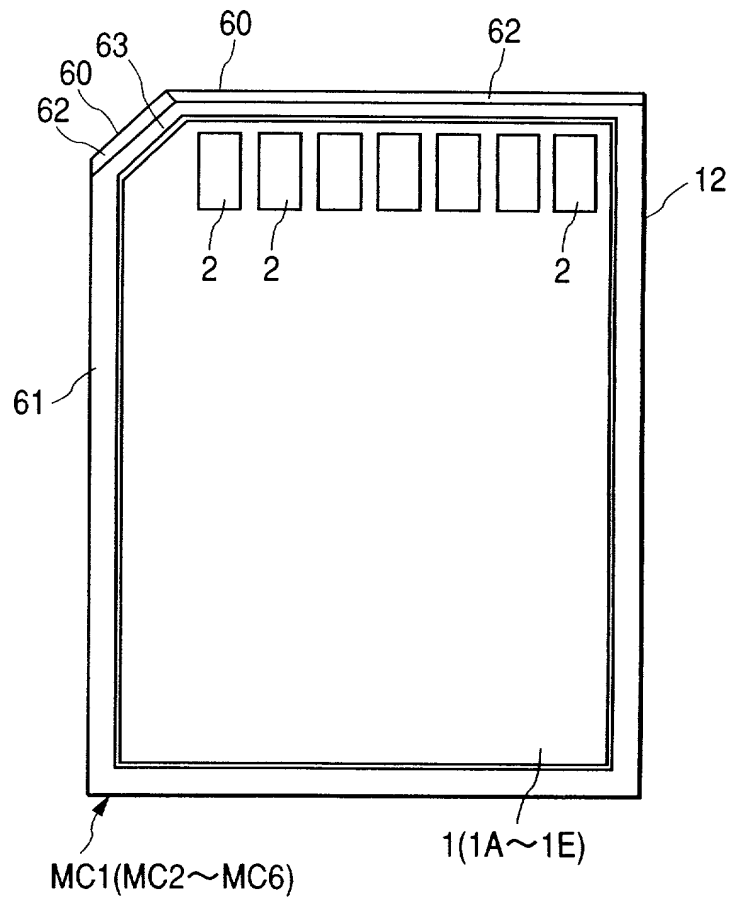


FIG. 27(B)

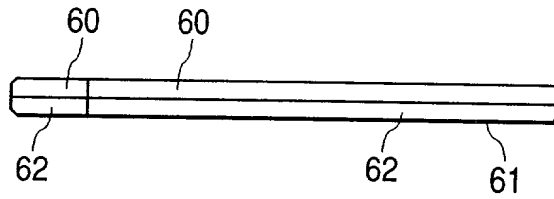


FIG. 27(C)

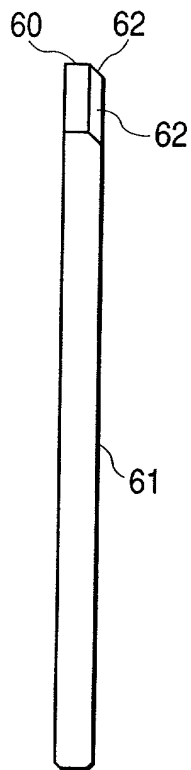


FIG. 27(A)

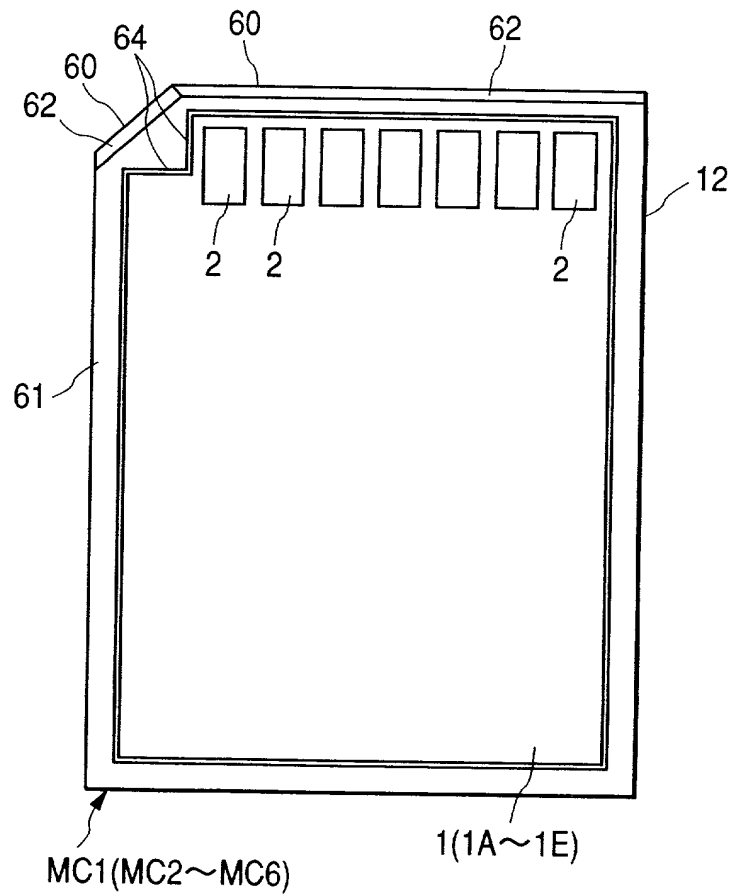


FIG. 28

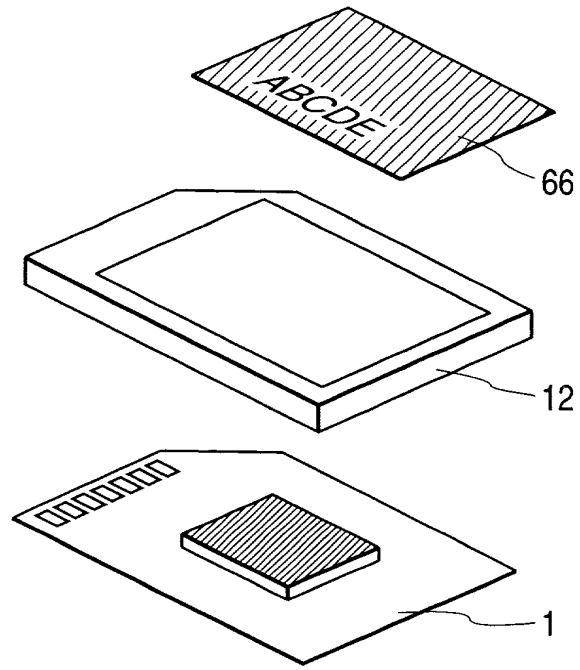


FIG. 29

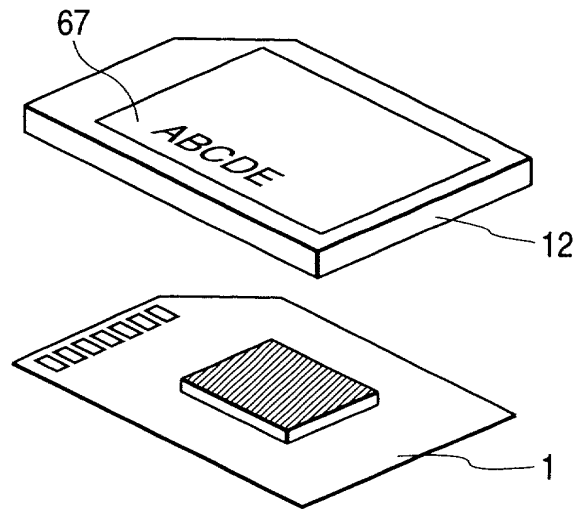


FIG. 30

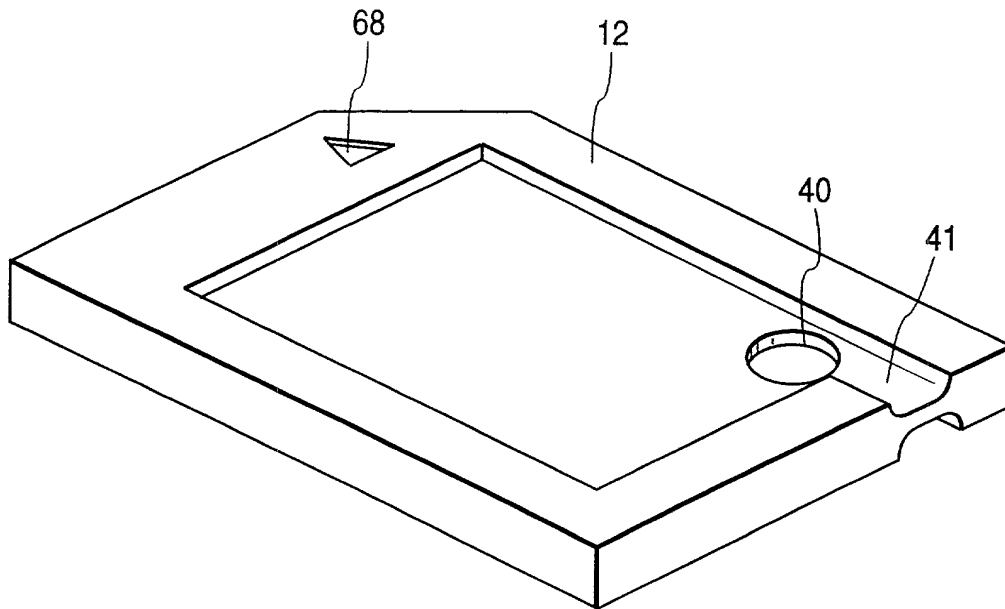


FIG. 31(B)

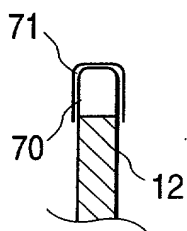


FIG. 31(A)

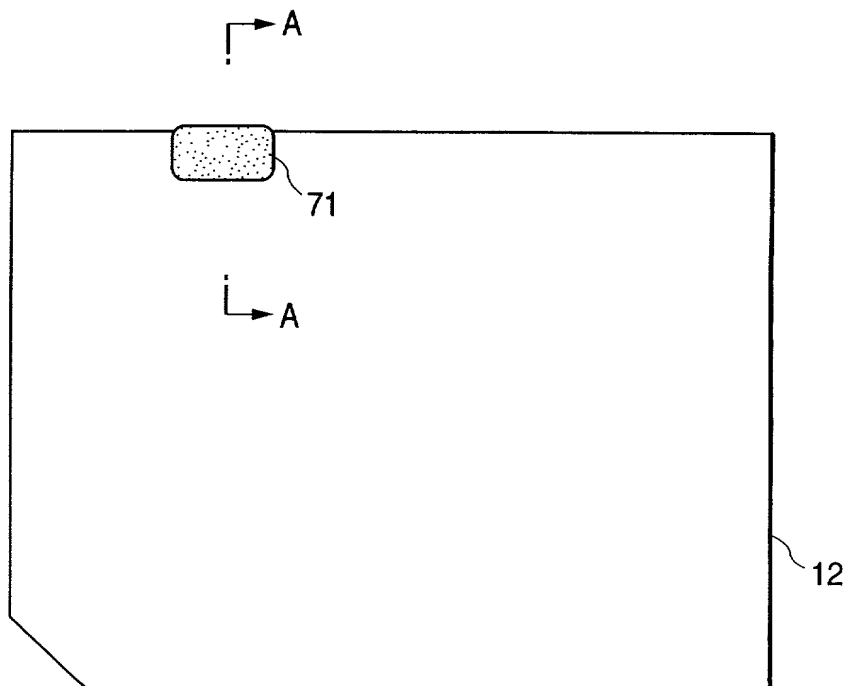


FIG. 32(A)

FIG. 32(B)

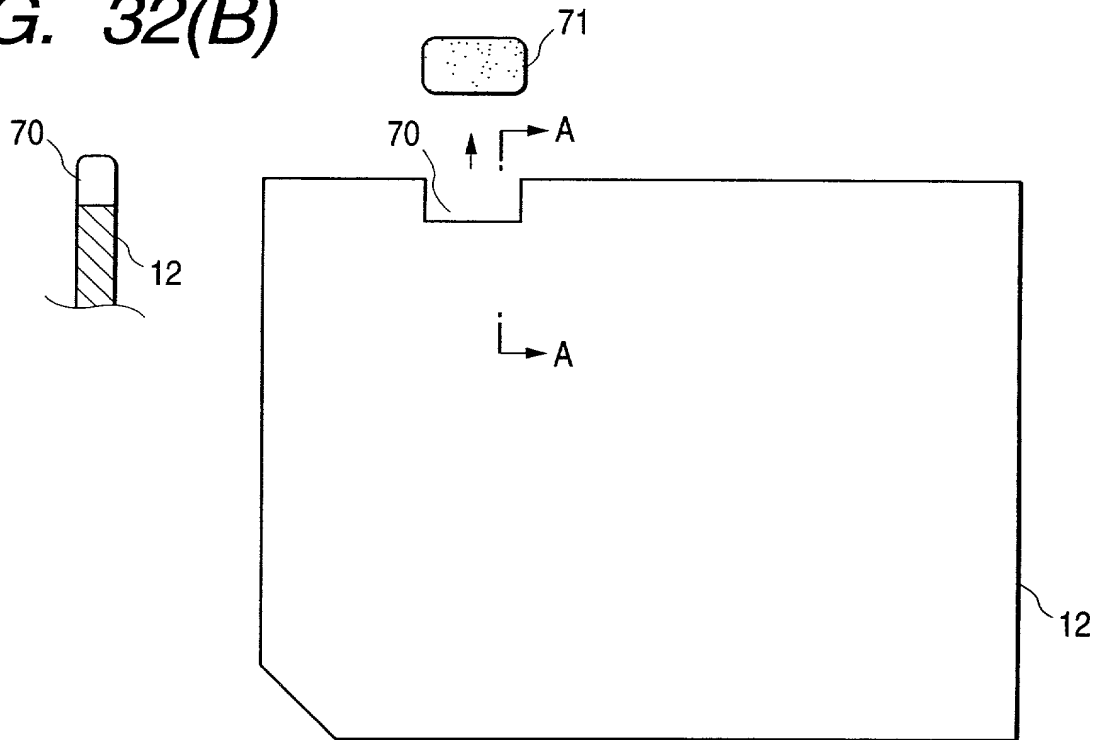


FIG. 33(B)

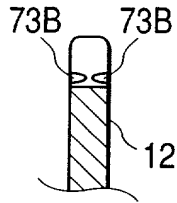


FIG. 33(A)

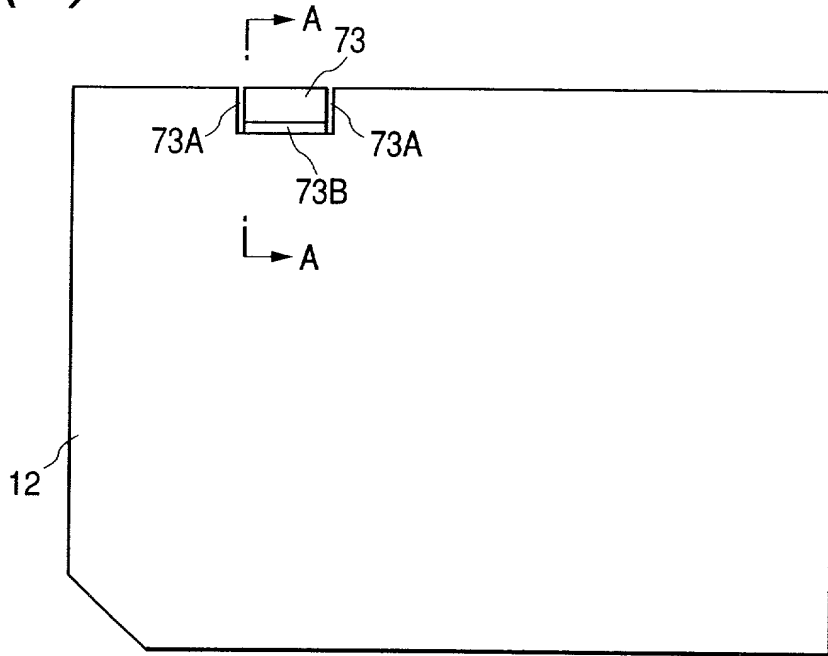


FIG. 34(B)

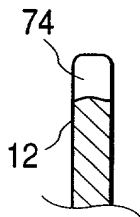


FIG. 34(A)

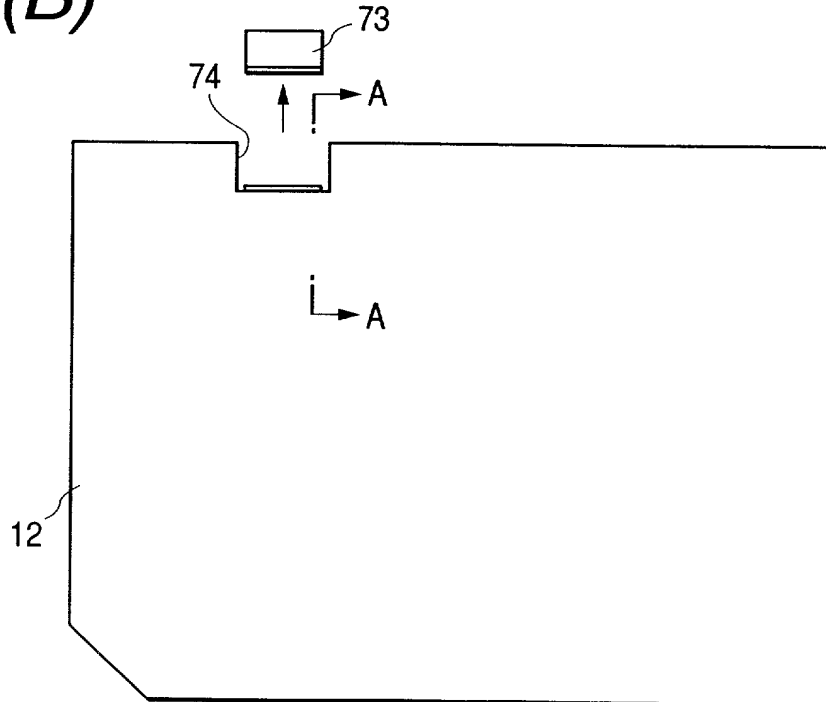


FIG. 35

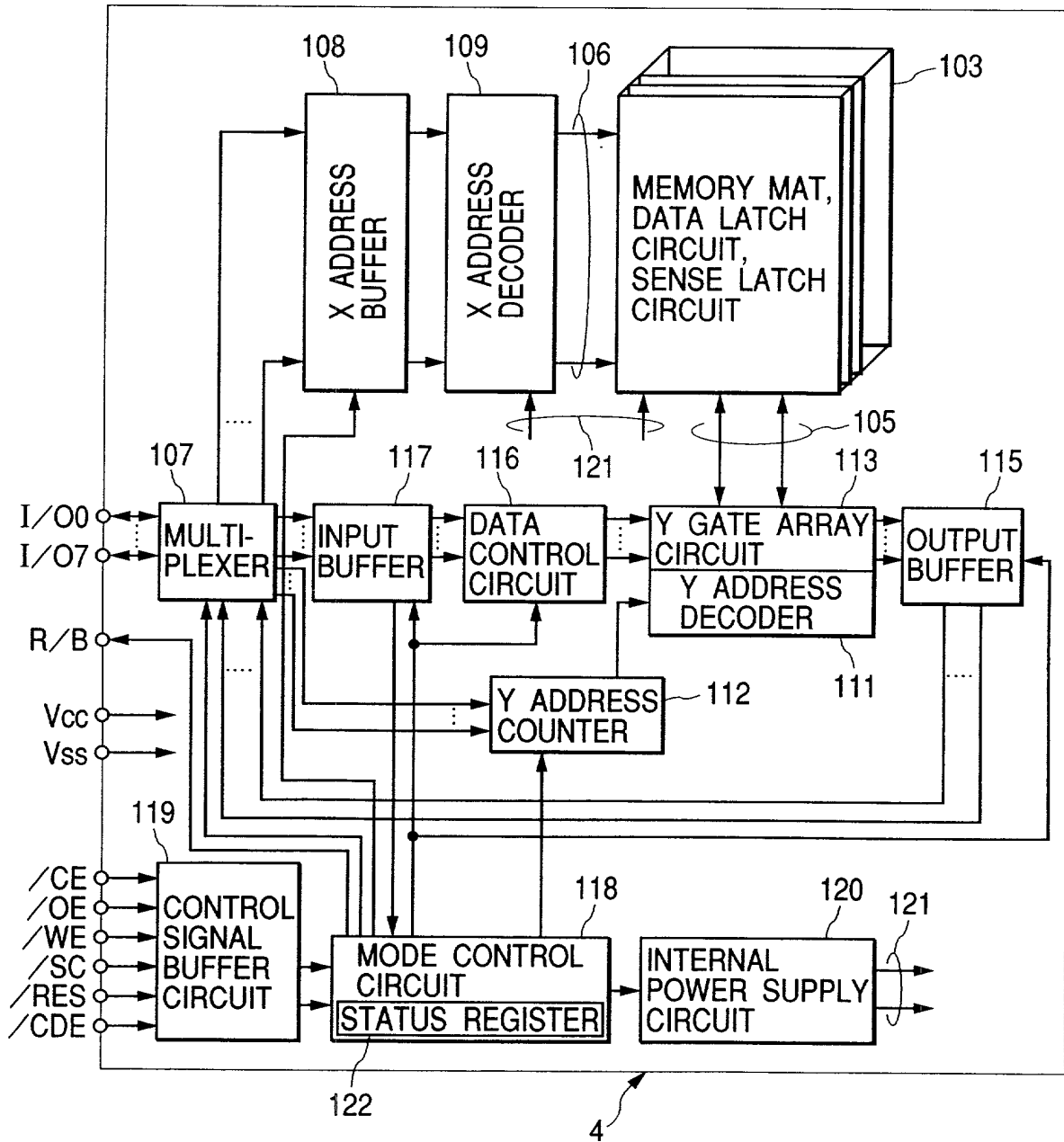


FIG. 36

